



ABSTRACT OF THE DISCLOSURE

A highly reliable multi-layer ceramic electronic part which is compact, in which cracks tend not to occur in the ceramic element even in cases where it is handled in bulk by a chip mounting device, and which is highly reliable, is provided. The thickness t_1 of a ceramic outer layer portion 6 of the multi-layer ceramic electronic part, in which a plurality of electrodes (internal electrodes) are disposed within a ceramic element whose length $L \leq 1.0\text{mm}$, height $H \leq 0.5\text{mm}$ and width $W \leq 0.5\text{mm}$, and the distance (thickness of the ceramic outer layer portion 6) t_1 from the internal electrode 2 (2a) of the outermost layer to the surface of the ceramic element 3 is 0.15mm or less, is $1/4$ or more of the thickness t_2 of the portion where the internal electrodes 2 are disposed.